

	Type	L #	Hits	Search Text	DBs	Time Stamp
1	BRS	L1	48	(resin and wafer and grind\$3 and (hole\$ or cut\$ or groove)).clm.	US-PGPUB	2005/08/03 20:11
2	BRS	L2	32	(resin and wafer and grind\$3 and (hole\$3 or cut\$3 or groove)).clm.	US-PGPUB	2005/08/03 20:24
3	BRS	L3	32	((resin protect\$4 support) and thick\$4 and wafer and grind\$3 and (hole\$3 or cut\$3 or groove)).clm.	US-PGPUB	2005/08/03 20:28
4	BRS	L4	7	((resin protect\$4 support) with thick\$4 and wafer with grind\$3 and (hole\$3 or cut\$3 or groove)).clm.	US-PGPUB	2005/08/03 20:28
5	BRS	L5	71	((resin protect\$4 support) and thick\$4 and (substrate wafer) and grind\$3 and (hole\$3 or cut\$3 or groove)).clm.	US-PGPUB	2005/08/03 20:28
6	BRS	L6	21	((resin protect\$4 support) with thick\$4 and (substrate wafer) with grind\$3 and (hole\$3 or cut\$3 or groove)).clm.	US-PGPUB	2005/08/03 20:28